

Attorney's Docket No. 9180-12

SAD  
#2  
2.2 0-02  
PATENT  
11040 U.S. PTO  
10/044387  
01/11/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Curtis Grant Jones et al;

Serial No.: ~~not assigned yet~~ 10/044387

Filed: ~~concurrently herewith~~ 1-11-02

For: ELECTROPLATING METHODS INCLUDING MAINTAINING A DETERMINED  
ELECTROPLATING VOLTAGE AND RELATED SYSTEMS

Date: January 11, 2002

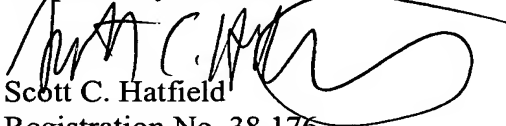
Box Patent Application  
Commissioner for Patents  
Washington, DC 20231

INFORMATION DISCLOSURE STATEMENT

Sir:

Attached is a list of documents on form PTO-1449 together with a copy of each identified document. It is requested that these documents be considered by the Examiner and officially made of record in accordance with the provisions of 37 C.F.R. § 1.97 and Section 609 of the MPEP. The Commissioner is hereby authorized to charge any additional fee, which may be required, or credit any refund, to our Deposit Account No. 50-0220.

Respectfully submitted,

  
Scott C. Hatfield  
Registration No. 38,176

Correspondence Address:



20792

PATENT TRADEMARK OFFICE

Tel (919) 854-1400

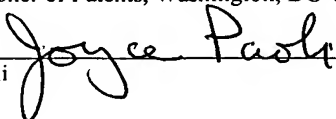
Fax (919) 854-1401

"Express Mail" mailing label number EL 733099245 US

Date of Deposit: January 11, 2002

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to Box Patent Application, Commissioner of Patents, Washington, DC 20231.

Joyce Paoli



## INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Sheet	1	of	1
-------	---	----	---

Application Number	not yet assigned
Filing Date	concurrently herewith
First Named Inventor	Curtis Grant Jones
Group Art Unit	
Examiner Name	not yet assigned
Attorney Docket Number	9180-12

11040 U.S. PRO  
10/044387  
01/11/02

[illegible][illegible]

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS			
Examiner Initials*	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published	T
	3.	Solomon " <i>Providing High Density and Performance for Chip-to System Interconnection</i> " Advanced Packaging (November 2001) pp 19-28	
	4.	Yung et al; " <i>Flip-Chip Process Utilizing Electroplated Solder Joints</i> "; Proceedings of the Technical Conference, (Sep. 10-12, 1990) International Electronics Packaging Conference Malborough, Massachusetts pp1065-1073	
Examiner Signature		Date Considered	

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.